



CB011-1R

October 2010

PRODUCT DESCRIPTION

CB011-1R provides the following product characteristics:

Technology	Epoxy
Appearance	Black liquid
Filler content, %	76
Product Benefits	• High purity • Low stress • High thermal conductivity capability • Minimal slumping
Cure	Heat cure
Operating Temperature	-65 to 140°C
Application	Encapsulant - dam

CB011-1R epoxy damming material is designed to be dispensed as a flow control barrier around areas of bare chip encapsulation and can be co-cured after encapsulation.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield - HBT, 25 °C, mPa·s (cP):

Spindle 14, speed 50 rpm	110,000
Thixotropic Index	2.5
Specific Gravity	1.8
Glob Height, mm	4
Gel Time @ 121°C, minutes	9
Pot Life @ 25°C, days	2
Shelf Life @ -40°C, months	6
Flash Point - See MSDS	

TYPICAL CURING PERFORMANCE

Cure Schedule

(Co-cure with Encapsulant)

2 hours @ 110°C plus 2 hours @ 160°C

(Co-cure with Filled version)

2 hours @ 150°C

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Coefficient of Thermal Expansion ppm/°C:

Below Tg	17
Above Tg	69
Glass Transition Temperature (Tg), °C	142

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

THAWING:

1. Allow container to reach room temperature before use.
2. Warm at room temperature until no longer cool to the touch (normally 20 to 60 minutes).
3. **NOTE:** Elevated temperatures reduce working life.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40°C. Storage below -40°C or greater than -40°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F

kV/mm x 25.4 = V/mil

mm / 25.4 = inches

N x 0.225 = lb

N/mm x 5.71 = lb/in

N/mm² x 145 = psi

MPa x 145 = psi

N·m x 8.851 = lb·in

N·m x 0.738 = lb·ft

N·mm x 0.142 = oz·in

mPa·s = cP

Note

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